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	Applicant Initia	ated Inte	rview Reques	t Form	
Application No.: 10/552	681	F	irst Named Applicant:	Roche Diagnostics	Operations, In
Examiner: Joel G. Horning Art Unit: 1792 Status of Application: Pending					Pending
Tentative Participants: (1) Attorney Timothy N.	Thomas	(2	Examiner Joel G. H	lorning	
(3)		(4)		
Proposed Date of Interv	iew: February 24, 201	0	Proposed Time	: 1:30 PM	AM/PM
Type of Interview Reque	ested:				
(1) 🗸 Telephonic (2) 🗌 Personal (3) 📗 Video Conference					
Exhibit To Be Shown or If yes, provide brief desc		Ť,	YES	NO	
Issues To Be Discussed					
Issues (Rej., Obj., etc)	Claims/ Fig. #s	Prior Art	Discuss	ed Agreed	Not Agreed
(1) 12		Wojnarowski et u US 5.302.547	al	. 🗆	~
(2)	-				
(3)					
(4)					
Continuation Shee	et Attached				
Brief Description of Argument to be Presented:					
Please See Attached She	eet				
An interview was conducted NOTE: This form shoul (see MPEP § 713.01). This application will not interview. Therefore, ap	d be completed by app be delayed from issue	licant and sub	omitted to the examin plicant's failure to su	er in advance of t bmit a written rec	ord of this
soon as possible.	plicant is advised to it	ie a statement	of the substance of th	is interview (57 C	FK 1.155(b)) as
Applicant/Applicant's Timothy N. Thomas Typed/Printed Name of	Representative Signative Applicant or Represen	- 1	Examiner	r/SPE Signature	·
	ber, if applicable				

This collection of information is required by 37 CFR 1.13a. The information is required to obtain or retain a benefit by the public which is to file (and by the USFTO to process) an application. Confidentially is governed by 33 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to take 21 minutes to complete, including substrainty, preparing using advantages of the completed application from the LUSFTO. Time will vary depending upon the individual case. Any commence on the incompleted in polication from the LUSFTO. Time will vary depending upon the individual case. Any commence on the incompleted in polication between the information of the incompleted polication on the incomplete displacement of the incompleted policy in the incomplete policy in the incompleted policy in the incomplete policy in the incompleted policy in the incompleted policy in the incompleted policy in the i If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2.

Re:

United States Patent Application No. 10/552,681

Filing Date: February 28, 2007

Title: METHOD FOR P

METHOD FOR PRODUCING MULTIPLE LAYER SYSTEMS

Inventor(s): Meier, Bhullar Our Ref.: 007404-000740

Applicants' claim 12 includes the limitation that an intermediate, "sacrificial" layer is used to selectively remove an adjacent non-conductive or metallic layer. In particular, a sacrificial layer (such as an organic polymer layer) is deposited adjacent a dielectric layer and photon energy is introduced into the sacrificial layer to ablate the sacrificial layer and thereby to remove either the non-conductive layer above or the metallic layer below. Applicants believe that that feature is neither taught nor suggested by Wojnarowski.

The pending Office Action appears to contend that Wojnarowski discloses applying energy to a sacrificial layer to remove either a non-conductive layer above or a metallic layer below. In particular, the Office Action appears to contend that Wojnarowski provides a non-conductive layer 76 adjacent an intermediate sacrificial (bi)layer 18/20, and uses laser energy to ablate the intermediate (bi)layer 18/20, thus removing the non-conductive layer 76.

Applicants' review of the Wojnarowski '547 patent suggests that the Wojnarowski non-conductive layer is removed by ablating it directly, and not by the ablation of an adjacent "sacrificial" layer. Wojnarowski discloses a non-conductive layer that overlies a dielectric layer, and Wojnarowski teaches that "[t]he nitride film is removed at the same time and in the same area during the laser ablation of second dielectric layer 20." Wojnarowski '547 at col. 7, lines 60-63. This appears to disclose using a laser to ablate both layers directly, rather than ablating only the intermediate/sacrificial layer and causing the non-conductive layer to be removed as a consequence of that ablation of the dielectric layer.

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